

DIANHYDRIDES BISDA

DESCRIPTION

BISDA (4,4-Bisphenol A Dianhydride) (dianhydrides of BPA) is a flake that can be used as a comonomer in polyimide synthesis or as an anhydride curing agent in epoxy. When used as an epoxy curative, BISDA can be used to enhance thermal performance in comparison to mono anhydrides and aromatic amine curing agents. Application areas include electronics encapsulation, composites, and adhesives. BISDA derived polyimide varnishes, coatings, adhesives, films and wire enamels meet desired solubility/stability in organic solvents even after complete imidization, heat resistance, flexibility/softness, dimensional stability and adhesion properties for ever-increasing design complexity of electronics devices.

GENERAL INFORMATION	
Features	No PFAS intentionally added
Fillers	Unreinforced
INDUSTRY	SUB INDUSTRY
Electrical and Electronics	Circuit Boards/Additives
Industrial	Industrial General

TYPICAL PROPERTY VALUES

Revision 20260605

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
PROPERTIES			
Melting Point	185 – 190	°C	
Boiling Point	>314	°C	
PHYSICAL			
Physical Form	Flake (>97% purity)	-	SABIC method
Mw	520.49	-	SABIC method
Solubility, Methyl Ethyl Ketone (75°C)	10	Wt. %	SABIC method

DISCLAIMER

Any sale by SABIC, its subsidiaries and affiliates (each a "seller"), is made exclusively under seller's standard conditions of sale (available upon request) unless agreed otherwise in writing and signed on behalf of the seller. While the information contained herein is given in good faith, SELLER MAKES NO WARRANTY, EXPRESS OR IMPLIED, INCLUDING MERCHANTABILITY AND NONINFRINGEMENT OF INTELLECTUAL PROPERTY, NOR ASSUMES ANY LIABILITY, DIRECT OR INDIRECT, WITH RESPECT TO THE PERFORMANCE, SUITABILITY OR FITNESS FOR INTENDED USE OR PURPOSE OF THESE PRODUCTS IN ANY APPLICATION. Each customer must determine the suitability of seller materials for the customer's particular use through appropriate testing and analysis. No statement by seller concerning a possible use of any product, service or design is intended, or should be construed, to grant any license under any patent or other intellectual property right.